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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









0.8A, 200V - 600V Surface Mount Super Fast Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Low power loss, high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

- Switching Mode Power Supplies
- Lighting
- On-board DC/DC converter

MECHANICAL DATA

- Case: SOD-123W
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 16mg (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _{F(AV)}	0.8	Α		
V_{RRM}	200 - 600	V		
I _{FSM}	20	Α		
T _{J MAX}	150	°C		
Package	SOD-123W			
Configuration	Single die			





SOD-123W

PARAMETER	SYMBOL	ESDLW	ESGLW	ESJLW	UNIT
Marking code on the device		EDLW	EGLW	EJLW	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	V
Forward current	I _{F(AV)}	0.8		Α	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	20		Α	
Junction temperature	TJ	-55 to +150		°C	
Storage temperature	T _{STG}	-55 to +150		°C	

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	34	°C/W			
Junction-to-ambient thermal resistance per diode	R _{OJA}	88	°C/W			
Junction-to-case thermal resistance per diode	R _{eJC}	35	°C/W			

Thermal Performance Note: Units mounted on recommended PCB (5mm x 5mm Cu pad test board)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
		$I_F = 0.4A, T_J = 25^{\circ}C$		0.80	-	V
	ESDLW	I _F = 0.8A, T _J = 25°C		0.85	0.95	V
		I _F = 0.4A, T _J = 125°C		0.65	-	V
		$I_F = 0.8A, T_J = 125^{\circ}C$		0.72	0.8	V
	ESGLW	$I_F = 0.4A, T_J = 25^{\circ}C$	V _F	0.88	-	V
F		$I_F = 0.8A, T_J = 25^{\circ}C$		0.96	1.3	V
Forward voltage per diode (1)		$I_F = 0.4A, T_J = 125^{\circ}C$		0.69	-	V
		$I_F = 0.8A, T_J = 125^{\circ}C$		0.77	1.05	V
	ESJLW	$I_F = 0.4A, T_J = 25^{\circ}C$		1.03	-	V
		$I_F = 0.8A, T_J = 25^{\circ}C$		1.14	1.7	V
		$I_F = 0.4A, T_J = 125^{\circ}C$		0.82	-	V
		$I_F = 0.8A, T_J = 125^{\circ}C$		0.94	1.3	V
Reverse current @ rated V _R per diode (2)		T _J = 25°C	1	-	1	μΑ
		T _J = 125°C	l _R	-	150	μΑ
	ESDLW		CJ	21	-	pF
Junction capacitance	ESGLW	1 MHz, V _R =4.0V		20	-	pF
	ESJLW			19	-	pF
Reverse recovery time		I _F =0.5A , I _R =1.0A I _{RR} =0.25A	t _{rr}	-	35	ns

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms



ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX(*)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ESxLW	1.1	RV	G	SOD-123W	3,000 / 7" Plastic Reel
(Note 1,2)	H 	RQ	G	SOD-123W	10,000 / 13" Paper Reel

Notes:

- 1. "x" defines voltage from 200V (ESDLW) to 600V (ESJLW)
- 2. Whole series with green compound (halogen-free)
- *: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ESDLWHRVG	ESDLW	Н	RV	G	AEC-Q101 qualified Green compound



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

1 AVERAGE FORWARD CURRENT (A) 8.0 0.6 0.4 0.2 Heat sink 5mm x 5mm Cu pad test board 0 100 25 50 75 125 150 LEAD TEMPERATURE (C)

Fig.2 Typical Junction Capacitance

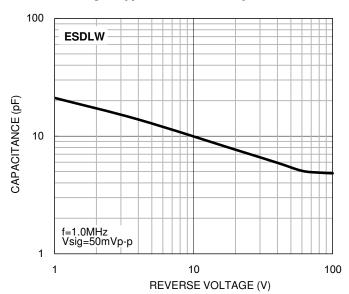


Fig.3 Typical Reverse Characteristics

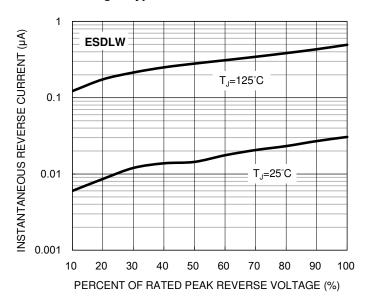
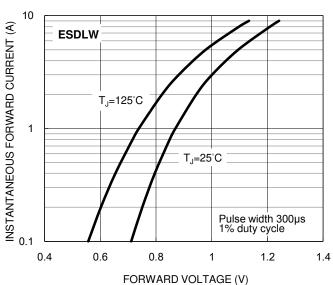


Fig.4 Typical Forward Characteristics





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.5 Typical Junction Capacitance

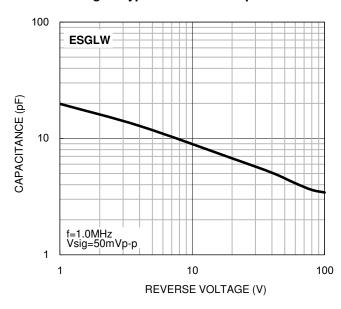


Fig.6 Typical Reverse Characteristics

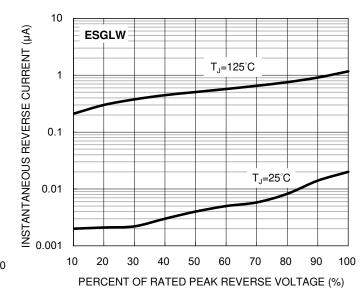
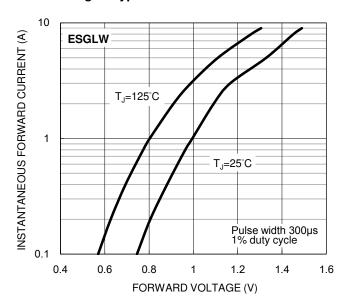


Fig.7 Typical Forward Characteristics





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.8 Typical Junction Capacitance

100

ESJLW

10

FSJLW

10

FSJLW

10

F=1.0MHz
Vsig=50mVp-p

1

1

10

REVERSE VOLTAGE (V)

Fig.9 Typical Reverse Characteristics

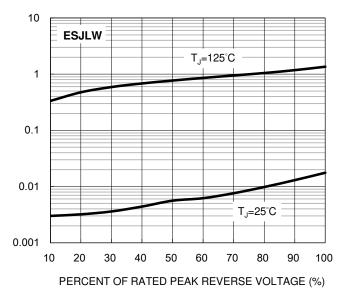
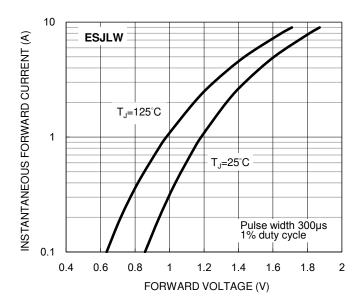


Fig.10 Typical Forward Characteristics

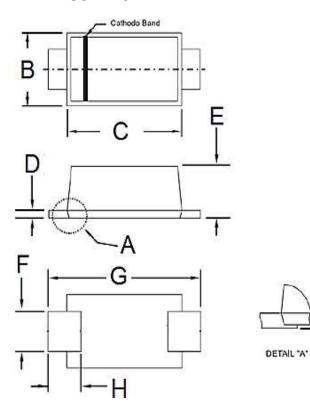


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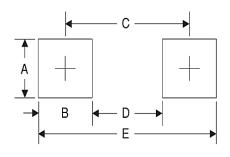
PACKAGE OUTLINE DIMENSIONS

SOD-123W



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
В	1.70	1.90	0.067	0.075	
С	2.60	2.90	0.102	0.114	
D	0.10	0.22	0.004	0.009	
E	0.90	1.02	0.035	0.040	
F	0.90	1.05	0.035	0.041	
G	3.60	3.80	0.142	0.150	
Н	0.50	0.85	0.020	0.033	
I	0.00	0.10	0.000	0.004	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.4	0.055
В	1.2	0.047
С	3.1	0.122
D	1.9	0.075
Е	4.3	0.169

MARKING DIAGRAM



P/N = Marking Code ΥW = Date Code F = Factory Code

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